

DUAL-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

Check for Samples: [SN74LVC2T45-EP](#)

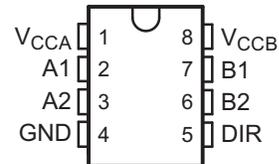
FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.65-V to 5.5-V Power-Supply Range
- V_{CC} Isolation Feature – If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State
- DIR Input Circuit Referenced to V_{CCA}
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Max Data Rates
 - 420 Mbps (3.3-V to 5-V Translation)
 - 210 Mbps (Translate to 3.3 V)
 - 140 Mbps (Translate to 2.5 V)
 - 75 Mbps (Translate to 1.8 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 4000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available Temperature Ranges:
 - -55°C to 125°C
 - -55°C to 150°C
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability

DCT OR DCU PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This dual-bit noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.65 V to 5.5 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.65 V to 5.5 V. This allows for universal low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

Table 1. ORDERING INFORMATION⁽¹⁾

| T_A | PACKAGE ⁽²⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|--|------------------------|-------------|-----------------------|------------------|
| -55°C to 125°C | SSOP – DCT | Reel of 250 | SN74LVC2T45MDCTTEP | NXR |
| -55°C to 150°C | SSOP – DCU | Reel of 250 | SN74LVC2T45SDCUT | CCVR |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74LVC2T45 is designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input activate either the B-port outputs or the A-port outputs. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports always is active and must have a logic HIGH or LOW level applied to prevent excess I_{CC} and I_{CCZ} .

The SN74LVC2T45 is designed so that the DIR input circuit is supplied by V_{CCA} .

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, both ports are in the high-impedance state.

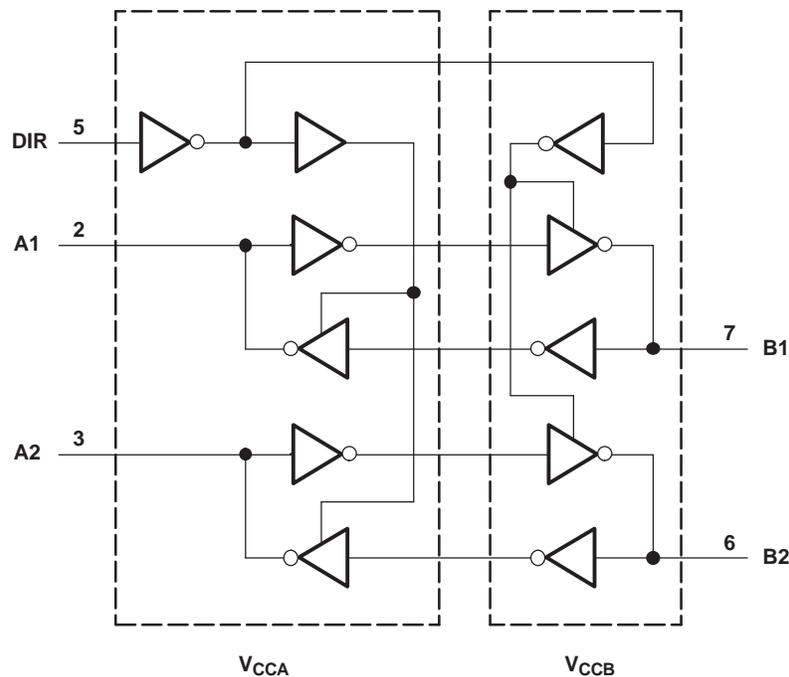
NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

**Table 2. FUNCTION TABLE⁽¹⁾
(EACH TRANSCEIVER)**

| INPUT DIR | OPERATION |
|-----------|-----------------|
| L | B data to A bus |
| H | A data to B bus |

(1) Input circuits of the data I/Os always are active.

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT | |
|------------------------|---|-----------|-------|-----------------|---|
| V_{CCA} V_{CCB} | Supply voltage range | -0.5 | 6.5 | V | |
| V_I | Input voltage range ⁽²⁾ | -0.5 | 6.5 | V | |
| V_O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | -0.5 | 6.5 | V | |
| V_O | Voltage range applied to any output in the high or low state ^{(2) (3)} | A port | -0.5 | $V_{CCA} + 0.5$ | V |
| | | B port | -0.5 | $V_{CCB} + 0.5$ | |
| I_{IK} | Input clamp current | $V_I < 0$ | -50 | mA | |
| I_{OK} | Output clamp current | $V_O < 0$ | -50 | mA | |
| I_O | Continuous output current | | ±50 | mA | |
| | Continuous current through V_{CC} or GND | | ±100 | mA | |
| θ_{JA} | Package thermal impedance ⁽⁴⁾ | DCT | 220 | °C/W | |
| | | DCU | 329.4 | | |
| T_{stg} | Storage temperature range | -65 | 150 | °C | |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions^{(1) (2) (3)}

| | | V_{CCI} | V_{CCO} | MIN | MAX | UNIT |
|---------------------|------------------------------------|---|------------------|-----------------------|-----------|------|
| V_{CCA} | Supply voltage | | | 1.65 | 5.5 | V |
| V_{CCB} | | | | 1.65 | 5.5 | |
| V_{IH} | High-level input voltage | Data inputs ⁽⁴⁾ | 1.65 V to 1.95 V | $V_{CCI} \times 0.65$ | V | |
| | | | 2.3 V to 2.7 V | 1.7 | | |
| | | | 3 V to 3.6 V | 2 | | |
| | | | 4.5 V to 5.5 V | $V_{CCI} \times 0.7$ | | |
| V_{IL} | Low-level input voltage | Data inputs ⁽⁴⁾ | 1.65 V to 1.95 V | $V_{CCI} \times 0.35$ | V | |
| | | | 2.3 V to 2.7 V | 0.7 | | |
| | | | 3 V to 3.6 V | 0.8 | | |
| | | | 4.5 V to 5.5 V | $V_{CCI} \times 0.3$ | | |
| V_{IH} | High-level input voltage | DIR (referenced to V_{CCA}) ⁽⁵⁾ | 1.65 V to 1.95 V | $V_{CCA} \times 0.65$ | V | |
| | | | 2.3 V to 2.7 V | 1.7 | | |
| | | | 3 V to 3.6 V | 2 | | |
| | | | 4.5 V to 5.5 V | $V_{CCA} \times 0.7$ | | |
| V_{IL} | Low-level input voltage | DIR (referenced to V_{CCA}) ⁽⁵⁾ | 1.65 V to 1.95 V | $V_{CCA} \times 0.35$ | V | |
| | | | 2.3 V to 2.7 V | 0.7 | | |
| | | | 3 V to 3.6 V | 0.8 | | |
| | | | 4.5 V to 5.5 V | $V_{CCA} \times 0.3$ | | |
| V_I | Input voltage | | | 0 | 5.5 | V |
| V_O | Output voltage | | | 0 | V_{CCO} | V |
| I_{OH} | High-level output current | | 1.65 V to 1.95 V | -4 | mA | |
| | | | 2.3 V to 2.7 V | -8 | | |
| | | | 3 V to 3.6 V | -24 | | |
| | | | 4.5 V to 5.5 V | -32 | | |
| I_{OL} | Low-level output current | | 1.65 V to 1.95 V | 4 | mA | |
| | | | 2.3 V to 2.7 V | 8 | | |
| | | | 3 V to 3.6 V | 24 | | |
| | | | 4.5 V to 5.5 V | 32 | | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | Data inputs | 1.65 V to 1.95 V | 20 | ns/V | |
| | | | 2.3 V to 2.7 V | 20 | | |
| | | | 3 V to 3.6 V | 10 | | |
| | | | 4.5 V to 5.5 V | 5 | | |
| | | Control input | 1.65 V to 5.5 V | 5 | | |
| T_A | Operating free-air temperature | DCT | | -55 | 125 | °C |
| | | DCU | | -55 | 150 | |

(1) V_{CCI} is the V_{CC} associated with the input port.

(2) V_{CCO} is the V_{CC} associated with the output port.

(3) All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(4) For V_{CCI} values not specified in the data sheet, V_{IH} min = $V_{CCI} \times 0.7$ V, V_{IL} max = $V_{CCI} \times 0.3$ V.

(5) For V_{CCI} values not specified in the data sheet, V_{IH} min = $V_{CCA} \times 0.7$ V, V_{IL} max = $V_{CCA} \times 0.3$ V.

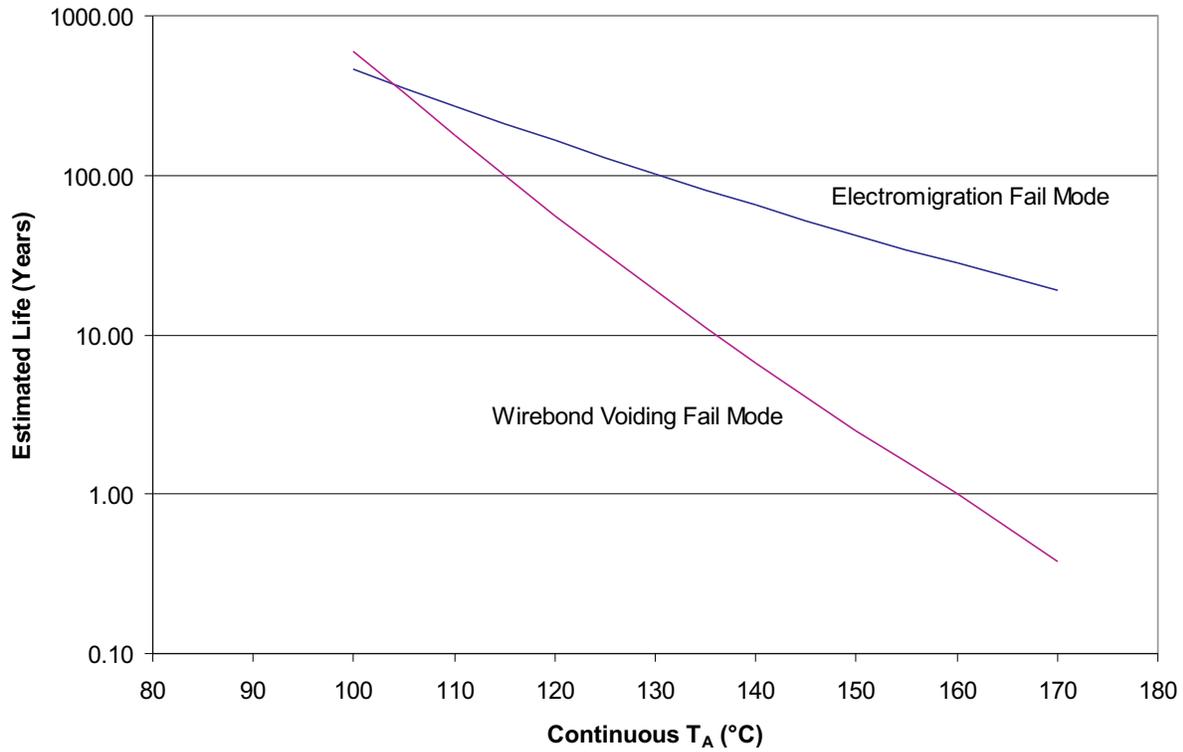
Electrical Characteristics^{(1) (2)}

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CCA} | V _{CCB} | T _A = 25°C | | -55°C to 125°C | | -55°C to 150°C | | UNIT | |
|--|-----------------|---|------------------|------------------|---|-----|------------------------|-----|------------------------|-----|------|------|
| | | | | | TYP | MAX | MIN | MAX | MIN | MAX | | |
| V _{OH} | | V _I = V _{IH} | 1.65 V to 4.5 V | 1.65 V to 4.5 V | | | V _{CCO} - 0.1 | | V _{CCO} - 0.1 | | V | |
| | | | 1.65 V | 1.65 V | | | 1.2 | | 1.2 | | | |
| | | | 2.3 V | 2.3 V | | | 1.9 | | 1.9 | | | |
| | | | 3 V | 3 V | | | 2.4 | | 2.4 | | | |
| | | | 4.5 V | 4.5 V | | | 3.8 | | 3.8 | | | |
| V _{OL} | | V _I = V _{IL} | 1.65 V to 4.5 V | 1.65 V to 4.5 V | | | | | 0.1 | | V | |
| | | | 1.65 V | 1.65 V | | | | | 0.45 | | | 0.45 |
| | | | 2.3 V | 2.3 V | | | | | 0.3 | | | 0.3 |
| | | | 3 V | 3 V | | | | | 0.55 | | | 0.55 |
| | | | 4.5 V | 4.5 V | | | | | 0.55 | | | 0.55 |
| I _I | DIR | V _I = V _{CCA} or GND | 1.65 V to 5.5 V | 1.65 V to 5.5 V | | ±1 | | ±2 | | ±2 | μA | |
| I _{off} | A port | V _I or V _O = 0 to 5.5 V | 0 V | 0 to 5.5 V | | ±1 | | ±9 | | ±9 | μA | |
| | B port | | 0 to 5.5 V | 0 V | | ±1 | | ±9 | | ±9 | | |
| I _{OZ} | A or B port | V _O = V _{CCO} or GND | 1.65 V to 5.5 V | 1.65 V to 5.5 V | | ±1 | | ±9 | | ±9 | μA | |
| I _{CCA} | | V _I = V _{CCI} or GND, I _O = 0 | 1.65 V to 5.5 V | 1.65 V to 5.5 V | | | | 4 | | 4 | μA | |
| | | | 5 V | 0 V | | | | 2 | | 2 | | |
| | | | 0 V | 5 V | | | | -12 | | -12 | | |
| I _{CCB} | | V _I = V _{CCI} or GND, I _O = 0 | 1.65 V to 5.5 V | 1.65 V to 5.5 V | | | | 4 | | 4 | μA | |
| | | | 5 V | 0 V | | | | -12 | | -12 | | |
| | | | 0 V | 5 V | | | | 2 | | 2 | | |
| I _{CCA} + I _{CCB} (see Table 3) | | V _I = V _{CCI} or GND, I _O = 0 | 1.65 V to 5.5 V | 1.65 V to 5.5 V | | | | 4 | | 4 | μA | |
| ΔI _{CCA} | A port | One A port at V _{CCA} - 0.6 V, DIR at V _{CCA} , B port = open | 3 V to 5.5 V | 3 V to 5.5 V | | | | 50 | | 50 | μA | |
| | DIR | | | | DIR at V _{CCA} - 0.6 V, B port = open, A port at V _{CCA} or GND | | | | 50 | | | 50 |
| ΔI _{CCB} | B port | One B port at V _{CCB} - 0.6 V, DIR at GND, A port = open | 3 V to 5.5 V | 3 V to 5.5 V | | | | 50 | | 50 | μA | |
| C _I | DIR | V _I = V _{CCA} or GND | 3.3 V | 3.3 V | | 2.5 | | | | | pF | |
| C _{io} | A or B port | V _O = V _{CCA/B} or GND | 3.3 V | 3.3 V | | 6 | | | | | pF | |

 (1) V_{CCO} is the V_{CC} associated with the output port.

 (2) V_{CCI} is the V_{CC} associated with the input port.



Notes:

1. See datasheet for absolute maximum and minimum recommended operating conditions.
2. Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).
3. Product disclaimer applies to DCU package 150°C.

Figure 1. LVC2T45SDCU Operating Life Derating Chart

Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ (unless otherwise noted) (see [Figure 2](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$ | | $V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$ | | $V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$ | | $V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$ | | UNIT |
|-----------------|--------------|-------------|--|------|---|------|---|------|---|------|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | A | B | 3 | 21.7 | 2.2 | 14.3 | 1.7 | 12.3 | 1.4 | 11.2 | ns |
| t_{PHL} | | | 2.8 | 28.3 | 2.2 | 12.5 | 1.8 | 11.1 | 1.7 | 11 | |
| t_{PLH} | B | A | 3 | 21.7 | 2.3 | 20 | 2.1 | 19.5 | 1.9 | 19.1 | ns |
| t_{PHL} | | | 2.8 | 18.3 | 2.1 | 16.9 | 2 | 16.6 | 1.8 | 16.2 | |
| t_{PHZ} | DIR | A | 10.6 | 34.9 | 10.3 | 34.5 | 10.5 | 34.5 | 10.7 | 33.3 | ns |
| t_{PLZ} | | | 7.3 | 23.7 | 7.5 | 23.6 | 7.5 | 23.5 | 7 | 23.4 | |
| t_{PHZ} | DIR | B | 10 | 31.9 | 8.4 | 18.9 | 6.5 | 15.3 | 4.1 | 12.6 | ns |
| t_{PLZ} | | | 6.5 | 23.5 | 7.2 | 16.6 | 4.3 | 13.7 | 2.1 | 11.1 | |
| $t_{PZH}^{(1)}$ | DIR | A | | 45.2 | | 36.6 | | 33.2 | | 30.2 | ns |
| $t_{PZL}^{(1)}$ | | | | 50.2 | | 35.8 | | 31.9 | | 28.8 | |
| $t_{PZH}^{(1)}$ | DIR | B | | 45.4 | | 37.9 | | 35.8 | | 34.6 | ns |
| $t_{PZL}^{(1)}$ | | | | 53.2 | | 47 | | 45.6 | | 44.3 | |

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted) (see [Figure 2](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$ | | $V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$ | | $V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$ | | $V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$ | | UNIT |
|-----------------|--------------|-------------|--|------|---|------|---|------|---|------|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | A | B | 2.3 | 20 | 1.5 | 12.5 | 1.3 | 10.4 | 1.1 | 9.1 | ns |
| t_{PHL} | | | 2.1 | 16.9 | 1.4 | 11.5 | 1.3 | 9.4 | 0.9 | 8.6 | |
| t_{PLH} | B | A | 2.2 | 14.3 | 1.5 | 12.5 | 1.4 | 12 | 1 | 11.5 | ns |
| t_{PHL} | | | 2.2 | 12.5 | 1.4 | 11.5 | 1.3 | 11 | 0.9 | 10.2 | |
| t_{PHZ} | DIR | A | 6.6 | 21.1 | 7.1 | 20.8 | 6.8 | 20.8 | 5.2 | 20.5 | ns |
| t_{PLZ} | | | 5.3 | 16.6 | 5.2 | 16.5 | 4.9 | 16.3 | 4.8 | 16.3 | |
| t_{PHZ} | DIR | B | 10.7 | 31.9 | 8.1 | 17.9 | 5.8 | 14.5 | 3.5 | 11.6 | ns |
| t_{PLZ} | | | 7.8 | 22.9 | 6.2 | 15.2 | 3.6 | 12.9 | 1.4 | 11.2 | |
| $t_{PZH}^{(1)}$ | DIR | A | | 37.2 | | 27.7 | | 24.9 | | 21.7 | ns |
| $t_{PZL}^{(1)}$ | | | | 44.4 | | 29.4 | | 25.5 | | 21.8 | |
| $t_{PZH}^{(1)}$ | DIR | B | | 26.6 | | 29 | | 26.7 | | 25.4 | ns |
| $t_{PZL}^{(1)}$ | | | | 38 | | 32.3 | | 30.2 | | 29.1 | |

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$ | | $V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ | | $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ | | $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$ | | UNIT |
|-----------------|--------------|-------------|--|------|---|------|---|------|---|------|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | A | B | 2.1 | 19.5 | 1.4 | 12 | 0.7 | 9.6 | 0.7 | 8.4 | ns |
| t_{PHL} | | | 2 | 16.6 | 1.3 | 11 | 0.8 | 9 | 0.7 | 8 | |
| t_{PLH} | B | A | 1.7 | 12.3 | 1.3 | 10.4 | 0.7 | 9.8 | 0.6 | 9.4 | ns |
| t_{PHL} | | | 1.8 | 11.1 | 1.3 | 9.4 | 0.8 | 9 | 0.7 | 8.5 | |
| t_{PHZ} | DIR | A | 5 | 14.9 | 5.1 | 14.8 | 5 | 14.8 | 5 | 14.4 | ns |
| t_{PLZ} | | | 3.4 | 12.4 | 3.7 | 12.4 | 3.9 | 12.1 | 3.3 | 11.8 | |
| t_{PHZ} | DIR | B | 11.2 | 31.3 | 8 | 17.7 | 5.8 | 14.4 | 2.9 | 11.4 | ns |
| t_{PLZ} | | | 9.4 | 21.7 | 5.6 | 15.3 | 4.3 | 12.3 | 1 | 9.6 | |
| $t_{PZH}^{(1)}$ | DIR | A | 34 | | 25.7 | | 22.1 | | 19 | | ns |
| $t_{PZL}^{(1)}$ | | | 42.4 | | 27.1 | | 23.4 | | 19.9 | | |
| $t_{PZH}^{(1)}$ | DIR | B | 31.9 | | 24.4 | | 21.9 | | 20.2 | | ns |
| $t_{PZL}^{(1)}$ | | | 31.5 | | 25.8 | | 23.8 | | 22.4 | | |

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$ | | $V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ | | $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ | | $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$ | | UNIT |
|-----------------|--------------|-------------|--|------|---|------|---|------|---|------|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | A | B | 1.9 | 19.1 | 1 | 11.5 | 0.6 | 9.4 | 0.5 | 7.9 | ns |
| t_{PHL} | | | 1.8 | 16.2 | 0.9 | 10.2 | 0.7 | 8.5 | 0.5 | 7.5 | |
| t_{PLH} | B | A | 1.4 | 11.2 | 1 | 9.1 | 0.7 | 8.4 | 0.5 | 7.9 | ns |
| t_{PHL} | | | 1.7 | 11 | 0.9 | 8.6 | 0.7 | 8 | 0.5 | 7.5 | |
| t_{PHZ} | DIR | A | 2.9 | 12.2 | 2.9 | 11.9 | 2.8 | 11.9 | 2.2 | 11.8 | ns |
| t_{PLZ} | | | 1.4 | 10.9 | 1.3 | 10.7 | 0.7 | 10.7 | 0.7 | 10.6 | |
| t_{PHZ} | DIR | B | 11.2 | 30.1 | 7.2 | 17.9 | 5.8 | 14.1 | 1.3 | 11.3 | ns |
| t_{PLZ} | | | 8.4 | 20.9 | 5 | 15 | 4 | 11.7 | 1 | 9.6 | |
| $t_{PZH}^{(1)}$ | DIR | A | 32.1 | | 24.1 | | 20.1 | | 18.5 | | ns |
| $t_{PZL}^{(1)}$ | | | 41.1 | | 26.5 | | 22.1 | | 18.8 | | |
| $t_{PZH}^{(1)}$ | DIR | B | 30 | | 22.2 | | 20.1 | | 18.5 | | ns |
| $t_{PZL}^{(1)}$ | | | 28.4 | | 22.1 | | 22.4 | | 19.3 | | |

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

Operating Characteristics

 $T_A = 25^\circ\text{C}$

| PARAMETER | | TEST CONDITIONS | $V_{CCA} =$ $V_{CCB} = 1.8\text{ V}$ | $V_{CCA} =$ $V_{CCB} = 2.5\text{ V}$ | $V_{CCA} =$ $V_{CCB} = 3.3\text{ V}$ | $V_{CCA} =$ $V_{CCB} = 5\text{ V}$ | UNIT |
|---------------|--------------------------------|---|---|---|---|---------------------------------------|------|
| | | | TYP | TYP | TYP | TYP | |
| C_{pdA} (1) | A-port input, B-port output | $C_L = 0\text{ pF},$ $f = 10\text{ MHz},$ $t_r = t_f = 1\text{ ns}$ | 3 | 4 | 4 | 4 | pF |
| | B-port input, A-port output | | 18 | 19 | 20 | 21 | |
| C_{pdB} (1) | A-port input, B-port output | $C_L = 0\text{ pF},$ $f = 10\text{ MHz},$ $t_r = t_f = 1\text{ ns}$ | 18 | 19 | 20 | 21 | pF |
| | B-port input, A-port output | | 3 | 4 | 4 | 4 | |

(1) Power dissipation capacitance per transceiver

Power-Up Considerations

A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies. To guard against such power-up problems, take the following precautions:

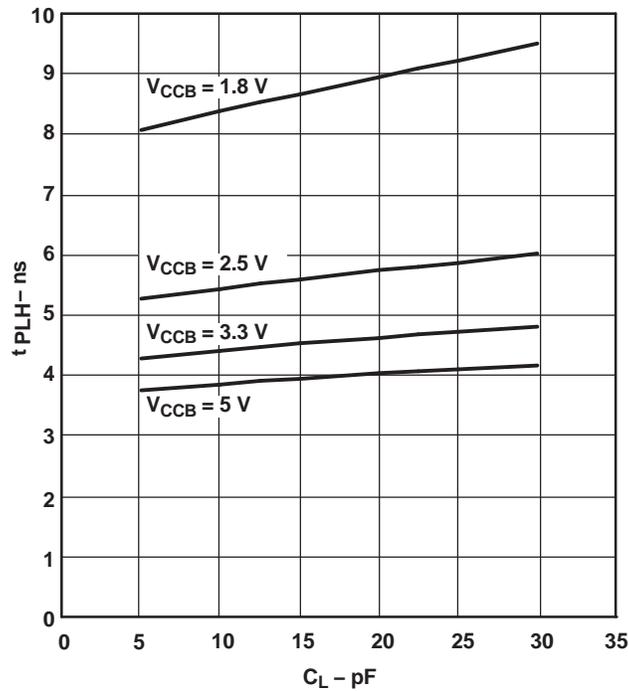
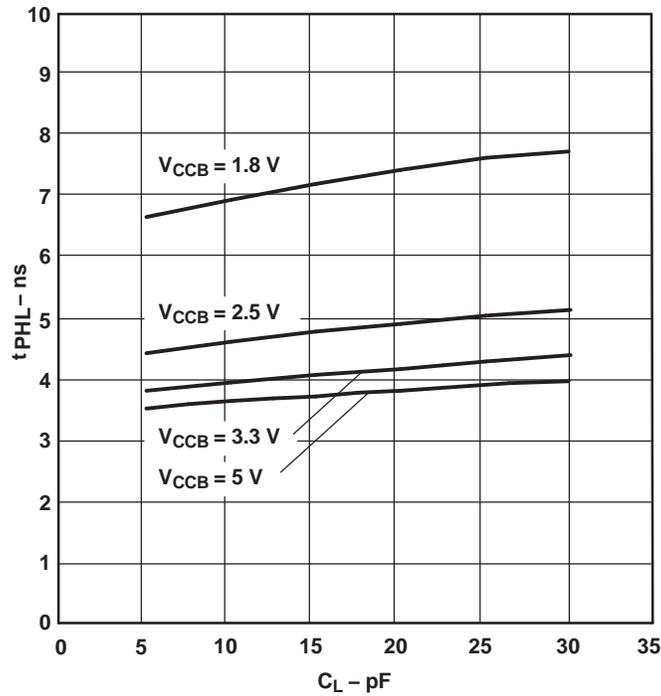
1. Connect ground before any supply voltage is applied.
2. Power up V_{CCA} .
3. V_{CCB} can be ramped up along with or after V_{CCA} .

Table 3. Typical Total Static Power Consumption ($I_{CCA} + I_{CCB}$)

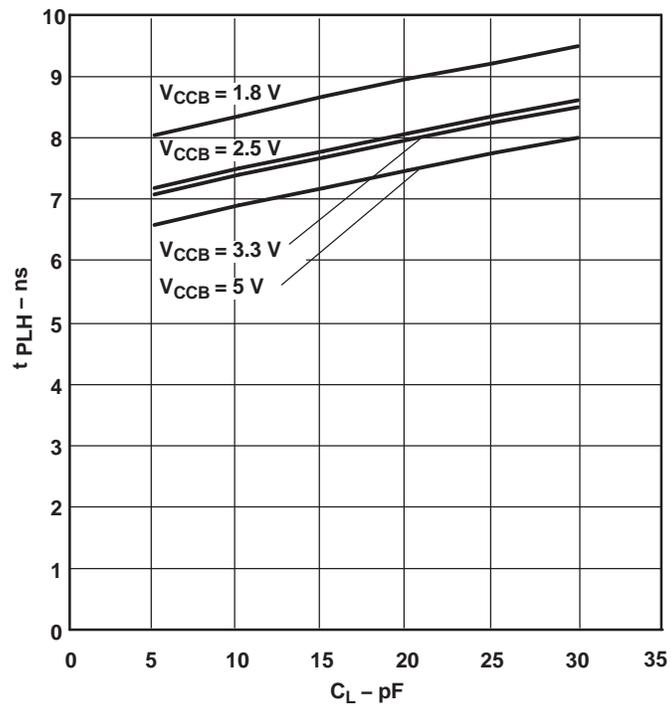
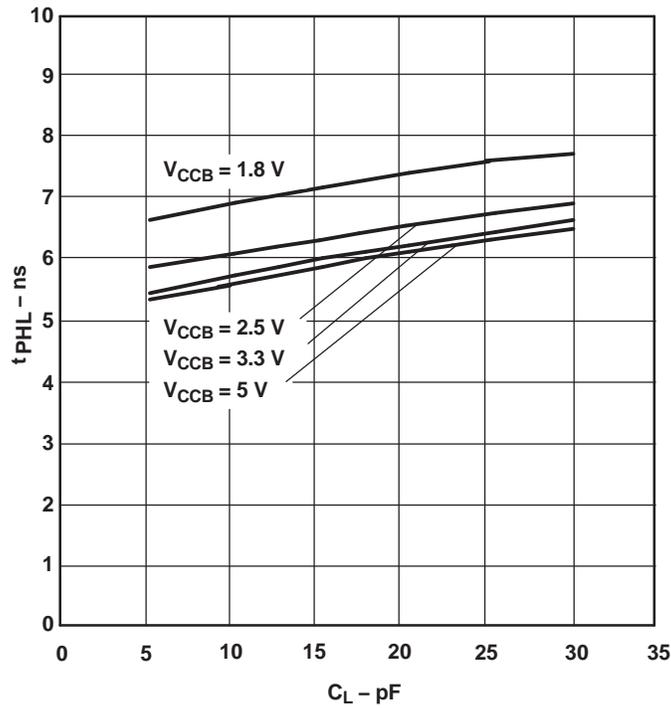
| V_{CCB} | V_{CCA} | | | | | UNIT |
|-----------|-----------|-------|-------|-------|-----|------|
| | 0 V | 1.8 V | 2.5 V | 3.3 V | 5 V | |
| 0 V | 0 | <1 | <1 | <1 | <1 | μA |
| 1.8 V | <1 | <2 | <2 | <2 | 2 | |
| 2.5 V | <1 | <2 | <2 | <2 | <2 | |
| 3.3 V | <1 | <2 | <2 | <2 | <2 | |
| 5 V | <1 | 2 | <2 | <2 | <2 | |

TYPICAL CHARACTERISTICS

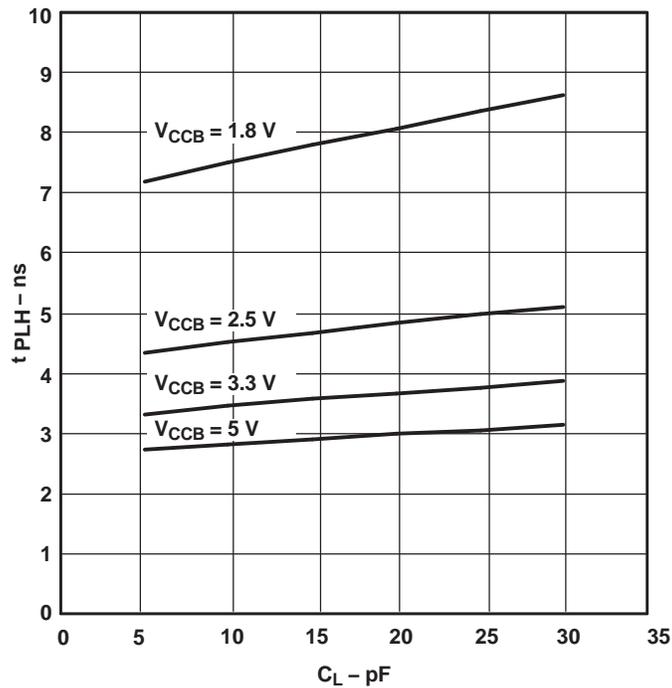
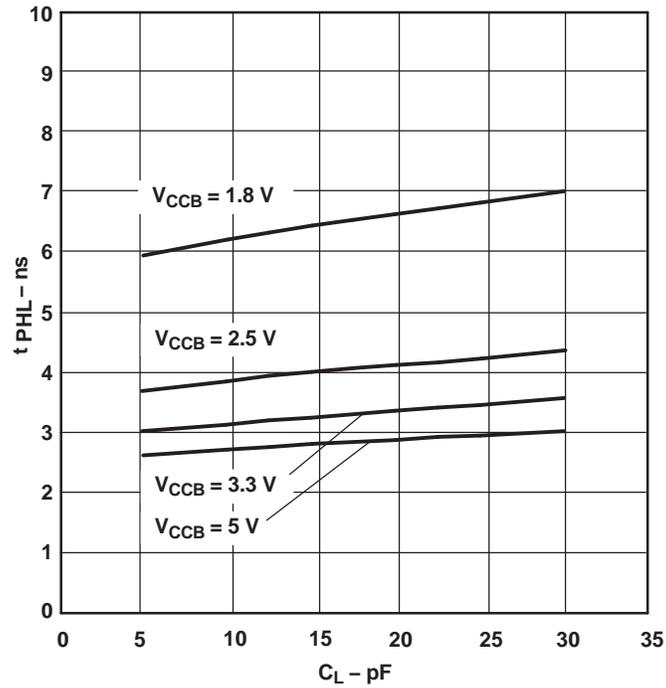
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}$, $V_{CCA} = 1.8\text{ V}$



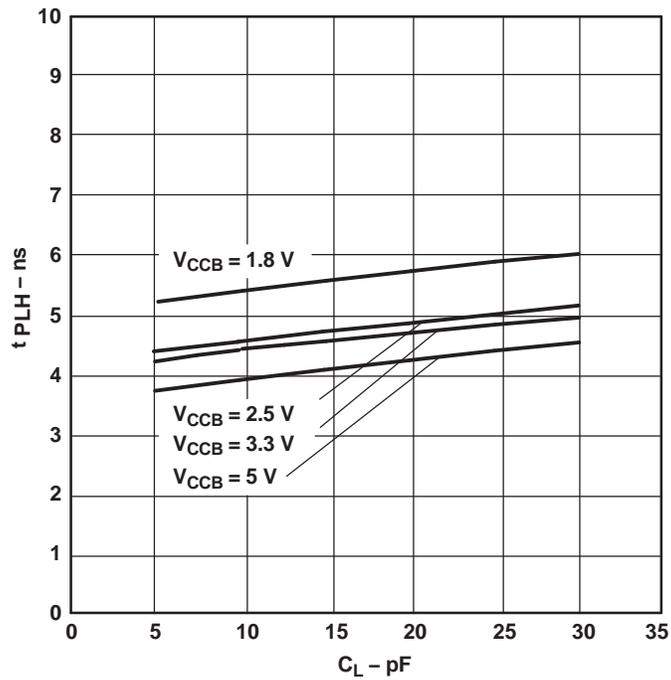
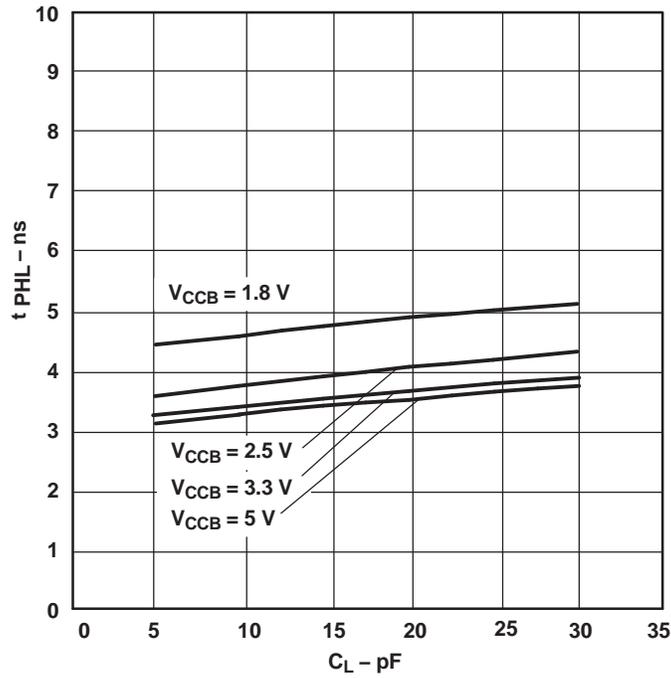
TYPICAL PROPAGATION DELAY (B to A) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}, V_{CCA} = 1.8\text{ V}$



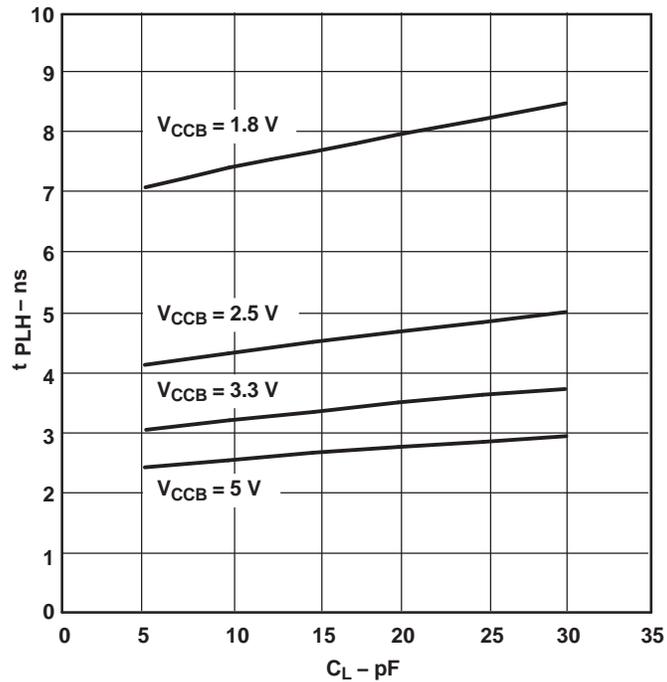
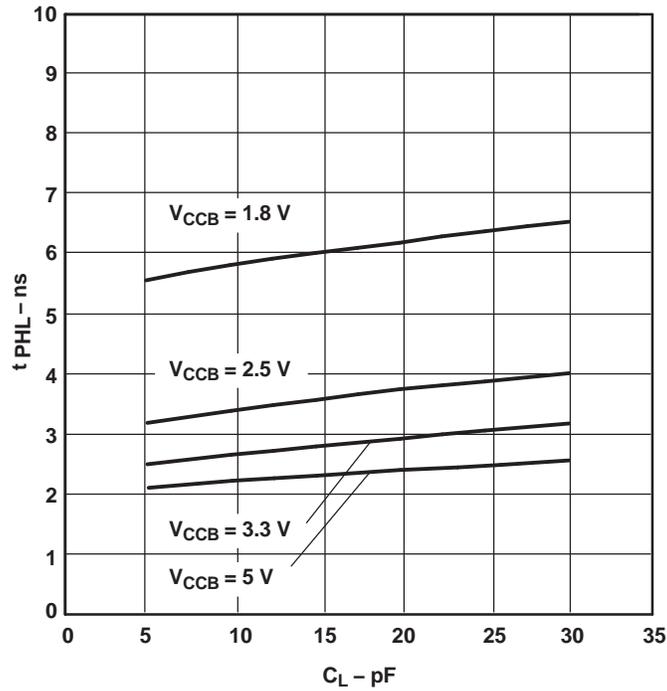
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}$, $V_{CCA} = 2.5\text{ V}$



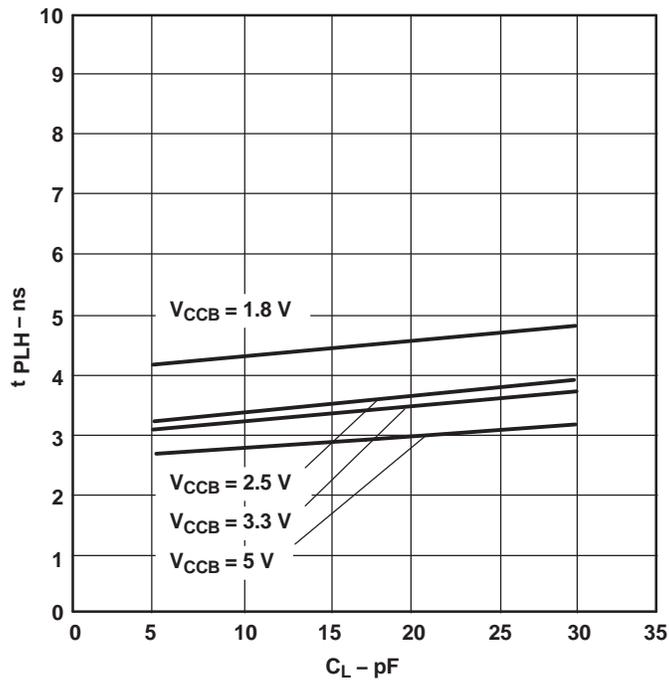
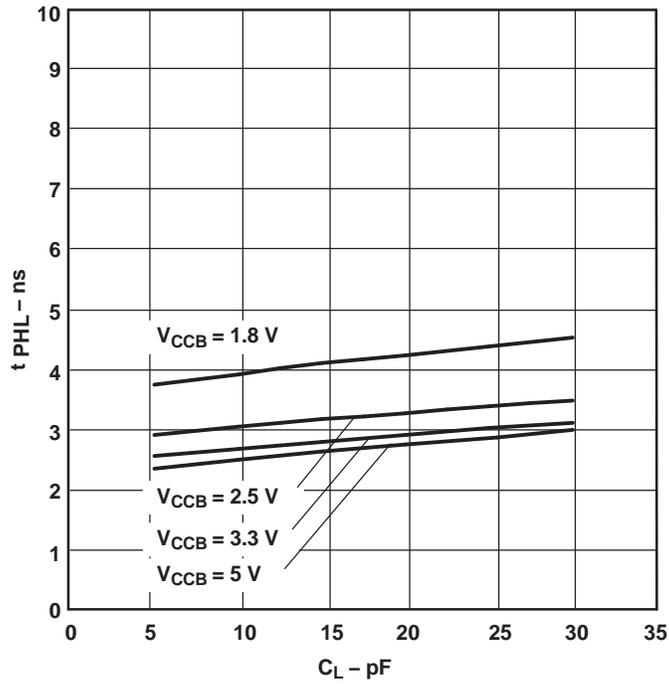
TYPICAL PROPAGATION DELAY (B to A) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}, V_{CCA} = 2.5\text{ V}$



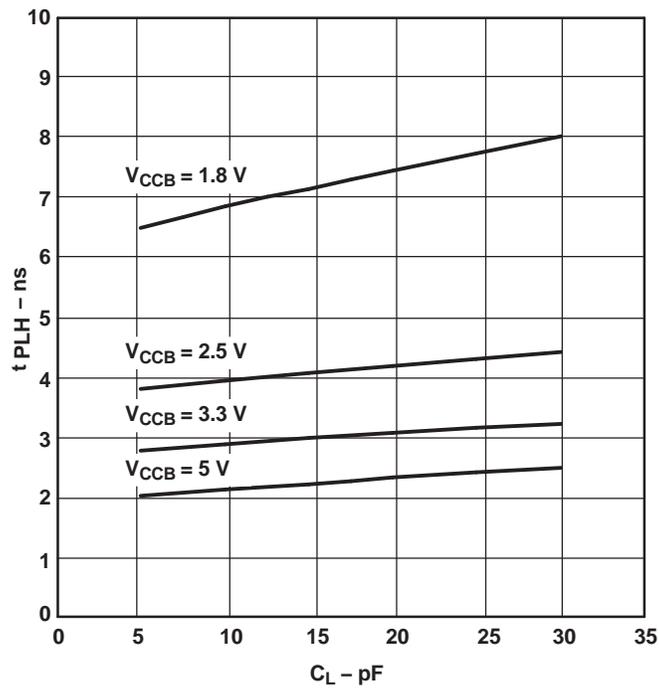
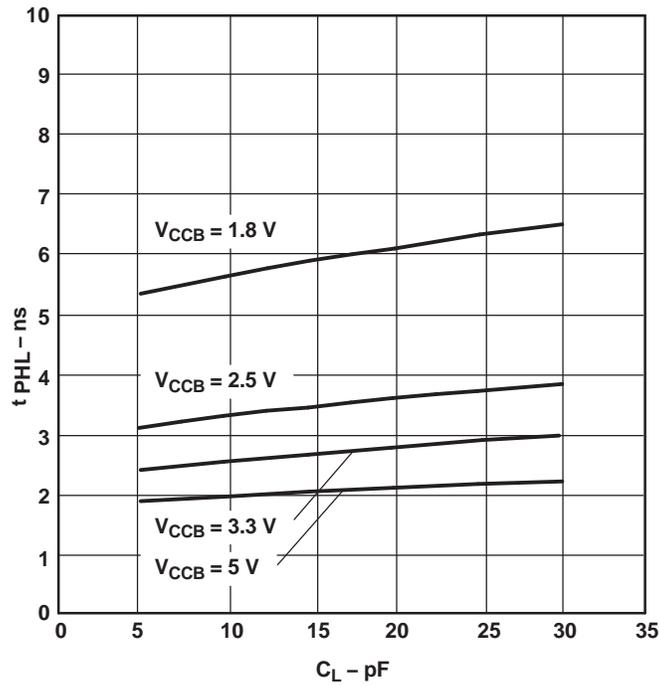
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}$, $V_{CCA} = 3.3\text{ V}$



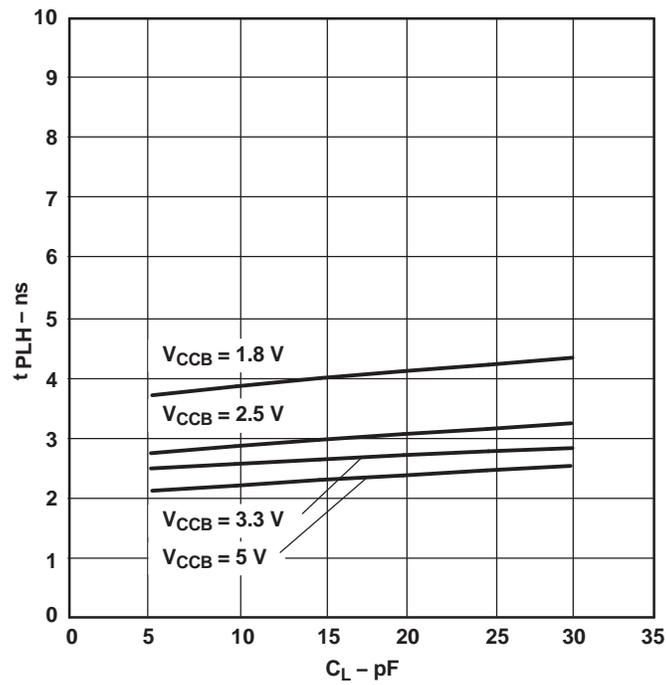
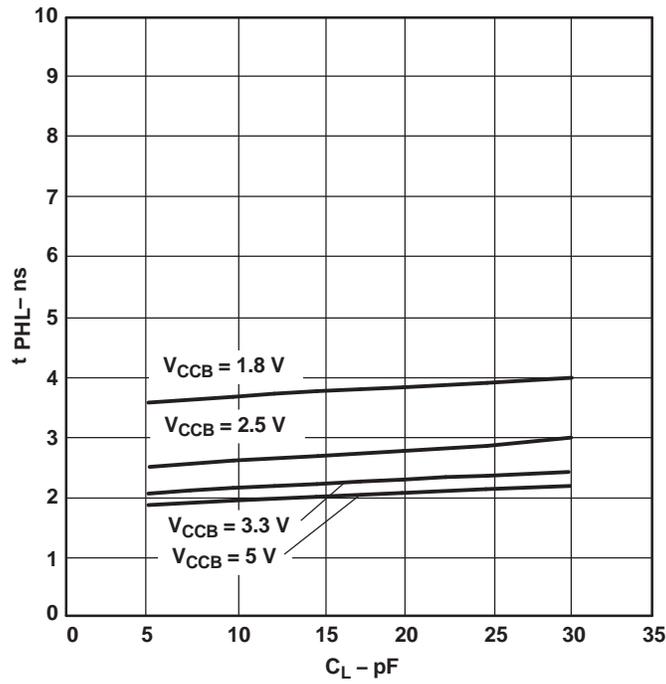
TYPICAL PROPAGATION DELAY (B to A) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}, V_{CCA} = 3.3\text{ V}$



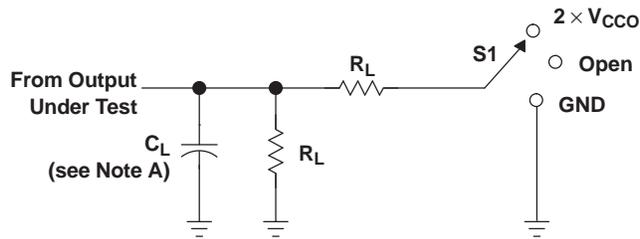
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}, V_{CCA} = 5\text{ V}$



TYPICAL PROPAGATION DELAY (B to A) vs LOAD CAPACITANCE
 $T_A = 25^\circ\text{C}, V_{CCA} = 5\text{ V}$



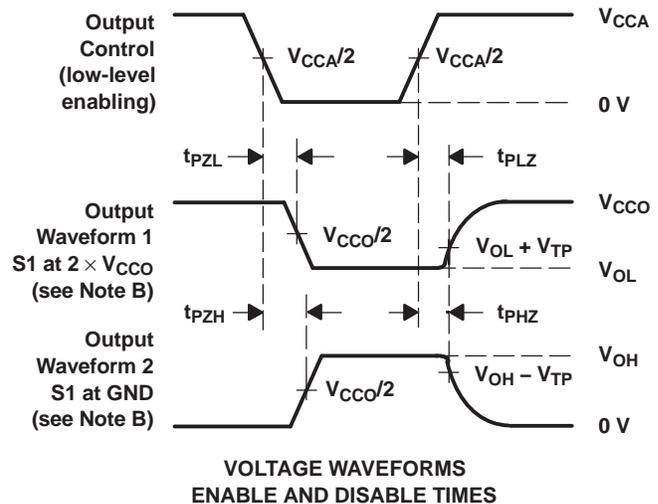
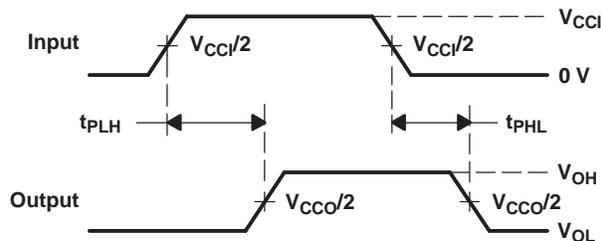
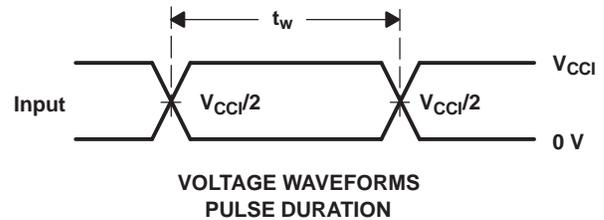
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

| TEST | S1 |
|-------------------|--------------------|
| t_{pd} | Open |
| t_{PLZ}/t_{PZL} | $2 \times V_{CCO}$ |
| t_{PHZ}/t_{PZH} | GND |

| V_{CCO} | C_L | R_L | V_{TP} |
|----------------------------------|-------|--------------|----------|
| $1.8\text{ V} \pm 0.15\text{ V}$ | 15 pF | 2 k Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | 15 pF | 2 k Ω | 0.15 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 15 pF | 2 k Ω | 0.3 V |
| $5\text{ V} \pm 0.5\text{ V}$ | 15 pF | 2 k Ω | 0.3 V |

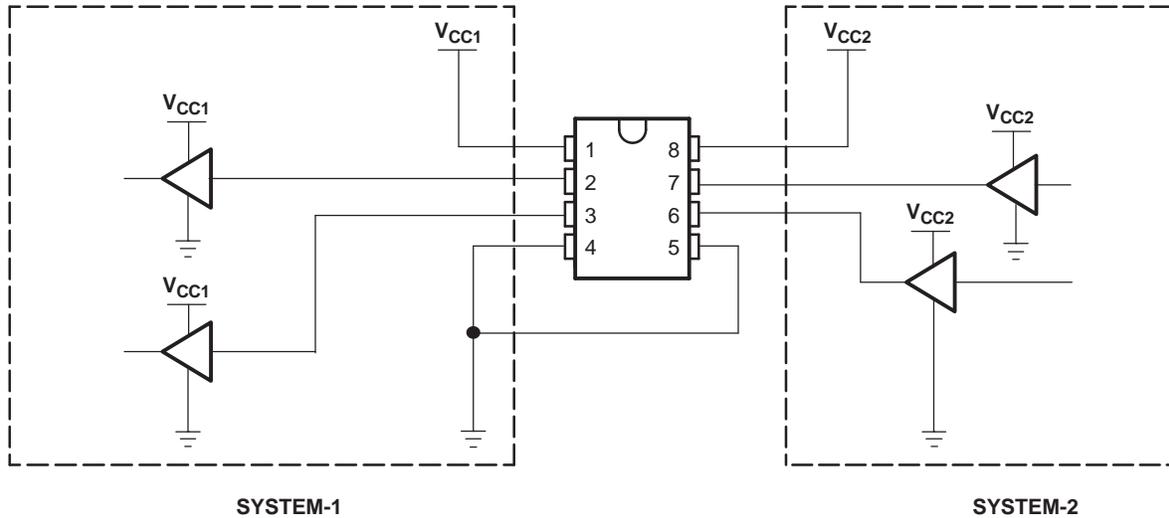


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $dv/dt \geq 1\text{ V/ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. V_{CC1} is the V_{CC} associated with the input port.
 - I. V_{CCO} is the V_{CC} associated with the output port.
 - J. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

APPLICATION INFORMATION

The following shows an example of the SN74LVC2T45 being used in a unidirectional logic level-shifting application.

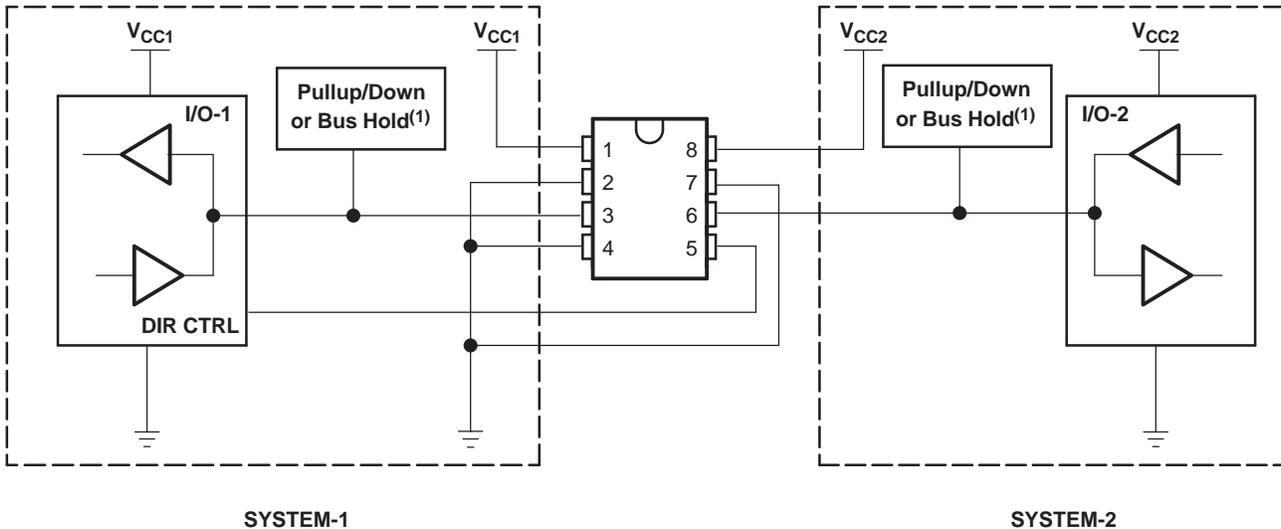


| PIN | NAME | FUNCTION | DESCRIPTION |
|-----|-----------|-----------|--|
| 1 | V_{CCA} | V_{CC1} | SYSTEM-1 supply voltage (1.65 V to 5.5 V) |
| 2 | A1 | OUT1 | Output level depends on V_{CC1} voltage. |
| 3 | A2 | OUT2 | Output level depends on V_{CC1} voltage. |
| 4 | GND | GND | Device GND |
| 5 | DIR | DIR | GND (low level) determines B-port to A-port direction. |
| 6 | B2 | IN2 | Input threshold value depends on V_{CC2} voltage. |
| 7 | B1 | IN1 | Input threshold value depends on V_{CC2} voltage. |
| 8 | V_{CCB} | V_{CC2} | SYSTEM-2 supply voltage (1.65 V to 5.5 V) |

Figure 3. Unidirectional Logic Level-Shifting Application

APPLICATION INFORMATION

Figure 4 shows the SN74LVC2T45 being used in a bidirectional logic level-shifting application. Since the SN74LVC2T45 does not have an output-enable (OE) pin, the system designer should take precautions to avoid bus contention between SYSTEM-1 and SYSTEM-2 when changing directions.



The following table shows data transmission from SYSTEM-1 to SYSTEM-2 and then from SYSTEM-2 to SYSTEM-1.

| STATE | DIR CTRL | I/O-1 | I/O-2 | DESCRIPTION |
|-------|----------|-------|-------|--|
| 1 | H | Out | In | SYSTEM-1 data to SYSTEM-2 |
| 2 | H | Hi-Z | Hi-Z | SYSTEM-2 is getting ready to send data to SYSTEM-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on pullup or pulldown. ⁽¹⁾ |
| 3 | L | Hi-Z | Hi-Z | DIR bit is flipped. I/O-1 and I/O-2 still are disabled. The bus-line state depends on pullup or pulldown. ⁽¹⁾ |
| 4 | L | In | Out | SYSTEM-2 data to SYSTEM-1 |

(1) SYSTEM-1 and SYSTEM-2 must use the same conditions, i.e., both pullup or both pulldown.

Figure 4. Bidirectional Logic Level-Shifting Application

Enable Times

Calculate the enable times for the SN74LVC2T45 using the following formulas:

- $t_{PZH} \text{ (DIR to A)} = t_{PLZ} \text{ (DIR to B)} + t_{PLH} \text{ (B to A)}$
- $t_{PZL} \text{ (DIR to A)} = t_{PHZ} \text{ (DIR to B)} + t_{PHL} \text{ (B to A)}$
- $t_{PZH} \text{ (DIR to B)} = t_{PLZ} \text{ (DIR to A)} + t_{PLH} \text{ (A to B)}$
- $t_{PZL} \text{ (DIR to B)} = t_{PHZ} \text{ (DIR to A)} + t_{PHL} \text{ (A to B)}$

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the SN74LVC2T45 initially is transmitting from A to B, then the DIR bit is switched; the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|---|
| SN74LVC2T45MDCTTEP | ACTIVE | SM8 | DCT | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | NXR Z |  |
| V62/09604-01XE | ACTIVE | SM8 | DCT | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | NXR Z |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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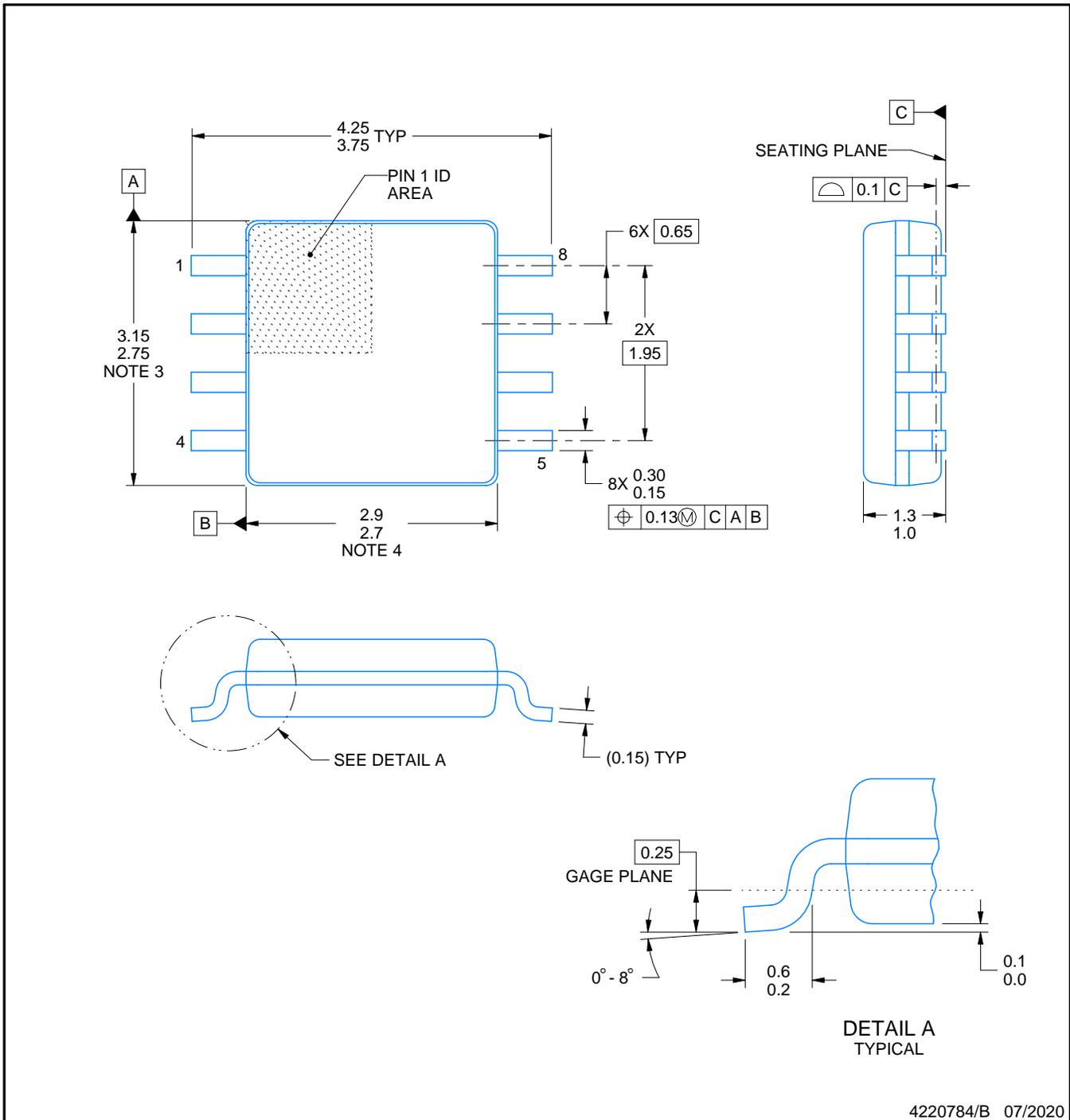
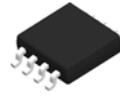
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OTHER QUALIFIED VERSIONS OF SN74LVC2T45-EP :

- Catalog: [SN74LVC2T45](#)
- Automotive: [SN74LVC2T45-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects



4220784/B 07/2020

NOTES:

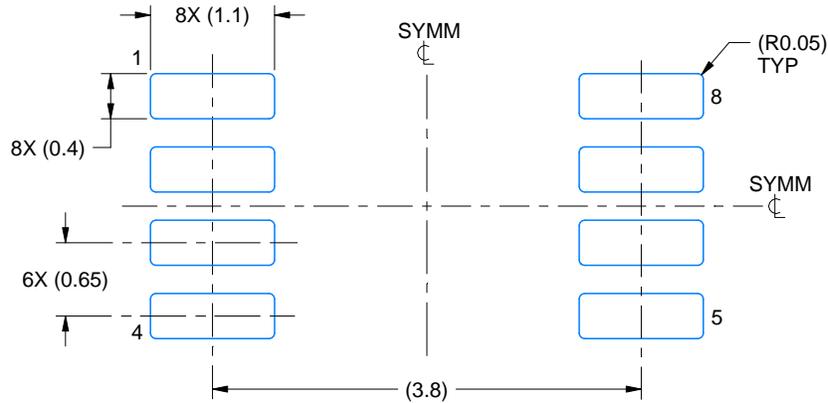
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MS-187.

EXAMPLE BOARD LAYOUT

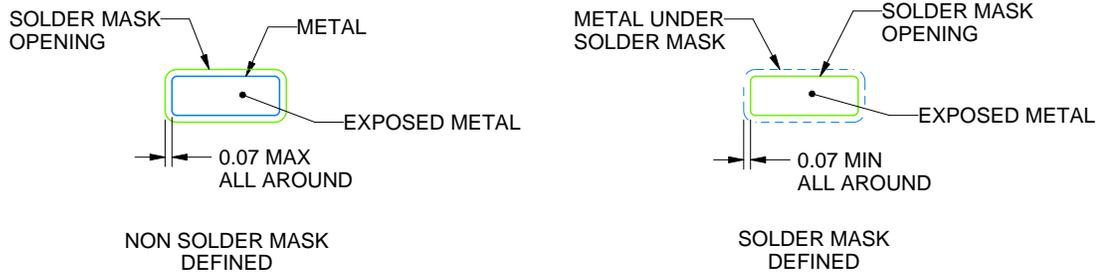
DCT0008A

SSOP - 1.3 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4220784/B 07/2020

NOTES: (continued)

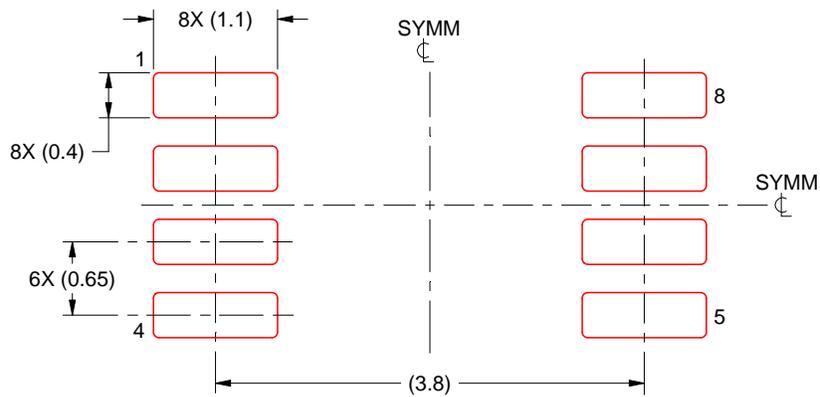
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCT0008A

SSOP - 1.3 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4220784/B 07/2020

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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